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SLUS896A-AUGUST 2009-REVISED AUGUST 2009

# **CURRENT MODE PWM CONTROLLER (KNOWN GOOD DIE)**

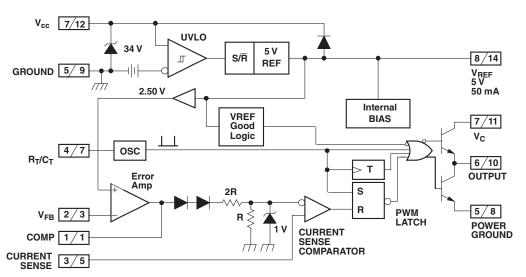
#### **FEATURES**

- -55°C to 125°C Known Good Die
- Controlled Baseline
- Optimized For Off-line and DC-to-DC Converters
- Low Start-Up Current (<1 mA)</li>
- Automatic Feed Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load Response Characteristics
- Under-Voltage Lockout With Hysteresis
- Double Pulse Suppression
- High Current Totem Pole Output
- Internally Trimmed Bandgap Reference
- 500-kHz Operation
- Low R<sub>O</sub> Error Amp

### **DESCRIPTION**

The UC1843 family of control devices provides the necessary features to implement off-line or dc-to-dc fixed frequency current mode control schemes with a minimal external parts count. Internally implemented circuits include under-voltage lockout featuring start up current less than 1 mA, a precision reference trimmed for accuracy at the error amp input, logic to insure latched operation, a PWM comparator which also provides current limit control, and a totem pole output stage designed to source or sink high peak current. The output stage, suitable for driving N-Channel MOSFETs, is low in the off state. The under-voltage lockout threshold is 8.4 V and maximum duty cycle range is around 100%.

#### **BLOCK DIAGRAM**



Note 1: A/B A = DIL-8 Pin NumberB = SO-14 and CFP-14 Pin Number

#### ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	KGD	UC1843KGD1	NA

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

<sup>(2)</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

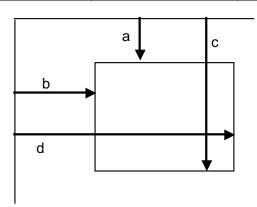


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### **BARE DIE INFORMATION**

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION		
15 mils.	Silicon with backgrind	GND	Al-Si-Cu (0.5%)		

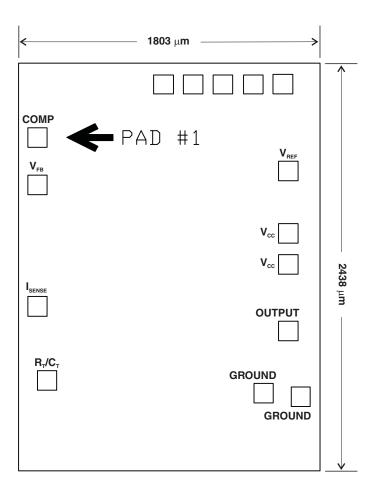


Origin

## **BOND PAD COORDINATES (in Mils)**

DESCRIPTION	PAD NUMBER	а	b	С	d
COMP	1	78.70	63.40	82.90	67.60
$V_{FB}$	2	70.60	63.40	74.80	67.60
I <sub>SENSE</sub>	3	39.40	63.40	43.60	67.60
$R_T/C_T$	4	18.60	61.20	22.60	65.60
GROUND	5	17.80	11.70	22.00	15.90
GROUND	6	17.40	3.90	21.80	8.10
OUTPUT	7	32.60	6.40	36.80	10.60
V <sub>cc</sub>	8	47.50	6.40	51.70	10.60
V <sub>CC</sub>	9	54.60	6.40	58.80	10.60
$V_{REF}$	10	68.70	6.40	72.90	10.60
NC	TESTPAD	87.10	6.30	90.80	10.30
NC	TESTPAD	87.10	12.60	90.80	16.60
NC	TESTPAD	87.10	18.00	90.80	22.00
NC	TESTPAD	87.10	24.30	90.80	28.30
NC	TESTPAD	87.10	30.60	90.80	34.60





### **ABSOLUTE MAXIMUM RATINGS**

		UNIT
0	Low impedance source	30 V
Supply voltage	I <sub>CC</sub> < 30 mA	Self Limiting
Output current		±1 A
Output energy (capacitive load)		5 ա
Analog inputs (Pins 2, 3)		−0.3 V to 6.3 V
Error amp output sink current		10 mA
Storage temperature range		−65°C to 150°C
Junction temperature range		−55°C to 150°C



### **ELECTRICAL CHARACTERISTICS**

Unless otherwise stated, these specifications apply for  $-55^{\circ}\text{C} \le T_{A} \le 125^{\circ}\text{C}$ ;  $V_{CC} = 15 \text{ V}^{(1)}$ ;  $R_{T} = 10 \text{ kW}$ ;  $C_{T} = 3.3 \text{ nF}$ ,  $T_{A} = T_{J.}$ 

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
REFERENCE SECTION	,				
Output Voltage	$T_J = 25^{\circ}C, I_O = 1 \text{ mA}$	4.95	5.00	5.05	V
Line Regulation	12 ≤ V <sub>IN</sub> ≤ 25 V		6	20	
Load Regulation	1 ≤ I <sub>0</sub> ≤ 20 mA		6	25	mV
Temperature Stability	See (2)(3)		0.2	0.4	mV/°C
Total Output Variation	Line, load, tempature (2)	4.9		5.1	V
Output Noise Voltage	10 Hz≤ f ≤ 10 kHz, T <sub>J</sub> = 25°C <sup>(2)</sup>		50		μV
Long Term Stability	T <sub>A</sub> = 125°C, 1000 Hrs <sup>(2)</sup>		5	25	mV
Output Short Circuit		-30	-100	-180	mA
OSCILLATOR SECTION		·			
Initial Accuracy	$T_J = 25^{\circ}C^{(4)}$	47	52	57	kHz
Voltage Stability	12 ≤ V <sub>CC</sub> ≤ 25 V		0.2%	1%	
Temperature Stability	$T_{MIN} \le T_A \le T_{MAX}$ (2)		5%		
Amplitude	V <sub>PIN</sub> 4 peak-to-peak <sup>(2)</sup>		1.7		V
ERROR AMP SECTION					
Input Voltage	V <sub>PIN 1</sub> = 2.5 V	2.45	2.50	2.55	V
Input Bias Current			-0.3	-1	μΑ
A <sub>VOL</sub>	2 ≤ V <sub>O</sub> ≤ 4 V	65	90		dB
Unity Gain Bandwidth	$T_{J} = 25^{\circ}C^{(2)}$	0.7	1		MHz
PSRR	12 ≤ V <sub>CC</sub> ≤ 25 V	60	70		dB
Output Sink Current	V <sub>PIN 2</sub> = 2.7 V, V <sub>PIN 1</sub> = 1.1 V	2	6		Λ
Output Source Current	V <sub>PIN 2</sub> = 2.3 V, V <sub>PIN 1</sub> = 5 V	-0.5	-0.8		mA
V <sub>OUT</sub> High	$V_{PIN 2} = 2.3 \text{ V}, R_L = 15 \text{ k}\Omega \text{ to ground}$	5	6		V
V <sub>OUT</sub> Low	$V_{PIN 2} = 2.7 \text{ V}, R_{L} = 15 \text{ k}\Omega \text{ to Pin 8}$		0.7	1.1	V
CURRENT SENSE SECTION		·			
Gain	See (5)(6)	2.85	3	3.15	V/V
Maximum Input Signal	V <sub>PIN 1</sub> = 5 V <sup>(5)</sup>	0.9	1	1.1	V
PSRR	$12 \le V_{CC} \le 25 \ V^{(2)(5)}$		70		dB
Input Bias Current			-2	-10	μΑ
Delay to Output	$V_{PIN 3} = 0 V to 2 V^{(2)}$		150	300	ns
OUTPUT SECTION					
Outrot I am I amal	I <sub>SINK</sub> = 20 mA		0.1	0.4	
Output Low Level	I <sub>SINK</sub> = 200 mA		1.5	2.2	V
Output High Lavel	I <sub>SOURCE</sub> = 20 mA	13	13.5		V
Output High Level	I <sub>SOURCE</sub> = 200 mA	12	13.5		
Rise Time	$T_J = 25^{\circ}C, C_L = 1 \text{ nF}^{(2)}$		50	150	
Fall Time	$T_J = 25^{\circ}C, C_L = 1nF^{(2)}$		50	150	ns

Temperature stability, sometimes referred to   
Temp Stability = 
$$\frac{V_{REF}(max) - V_{REF}(min)}{T_{J}(max) - T_{J}(min)}$$

TJ(max) - TJ (min)  $TJ(max) - TJ(min) V_{REF(max)} \text{ and } V_{REF(min)} \text{ are the maximum and minimum reference voltages measured over the appropriate temperature range. Note that the extremes in voltage do not necessarily occur at the extremes in temperature.}$ 

Output frequency equals oscillator frequency.

(5)

Parameter measured at trip point of latch with V<sub>PIN 2</sub> = 0.   
Gain defined as: 
$$A = \frac{\Delta V PIN \ 1}{\Delta V PIN \ 3}, \ 0 \le V PIN \ 3 \le 0.8 \ V$$

Gain defined as:

Adjust  $V_{CC}$  above the start threshold before setting at 15 V. These parameters, although specified, are not 100% tested in production.

Temperature stability, sometimes referred to as average temperature coefficient, is described by the equation:

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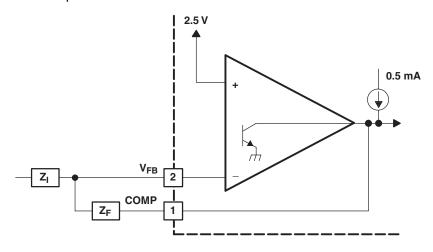
### **ELECTRICAL CHARACTERISTICS (continued)**

Unless otherwise stated, these specifications apply for  $-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le 125^{\circ}\text{C}; \text{ V}_{\text{CC}} = 15 \text{ V}; \text{ R}_{\text{T}} = 10 \text{ kW}; \text{ C}_{\text{T}} = 3.3 \text{ nF}, \text{T}_{\text{A}} = \text{T}_{\text{J}}$ 

PARAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
UNDER-VOLTAGE LOCKOUT SECT	ION		·		·	
Start Threshold			7.8	8.4	9.0	
Min. Operating Voltage After Turn On			7.0	7.6	8.2	V
PWM SECTION						
Maximum Duty Cycle			95%	97%	100%	
Minimum Duty Cycle					0%	
TOTAL STANDBY CURRENT	1		<u>"</u>			
Start-Up Current				0.5	1	Λ
Operating Supply Current	V <sub>PIN 2</sub> = V <sub>PIN 3</sub> = 0 V			11	17	mA
V <sub>CC</sub> Zener Voltager	I <sub>CC</sub> = 25 mA		30	34		V

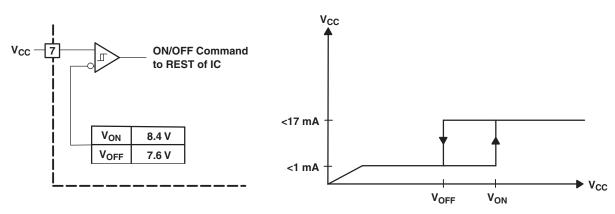
#### **ERROR AMP CONFIGURATION**

Error amp can source or sink up to 0.5 mA.



### **UNDER-VOLTAGE LOCKOUT**

During under-voltage lock-out, the output drive is biased to sink minor amounts of current. Pin 6 should be shunted to ground with a bleeder resistor to prevent activating the power switch with extraneous leakage currents.

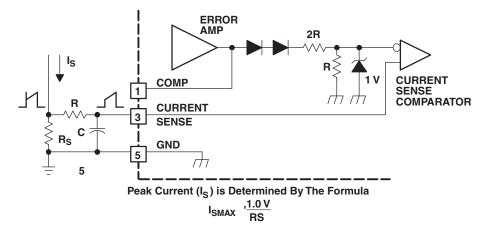


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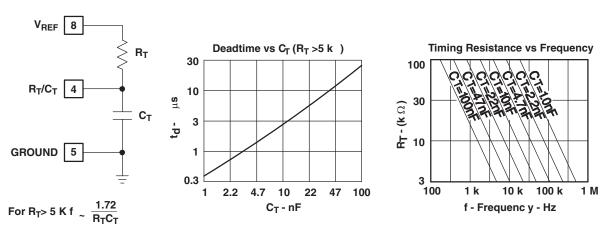


### **CURRENT SENSE CIRCUIT**

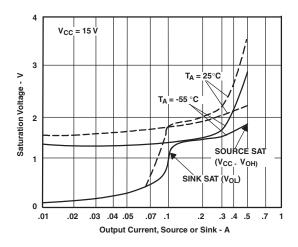
A small RC filter may be required to suppress switch transients.



### **OSCILLATOR SECTION**

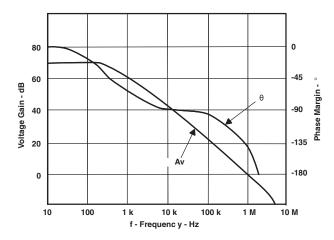


#### **OUTPUT SATURATION CHARACTERISTICS**



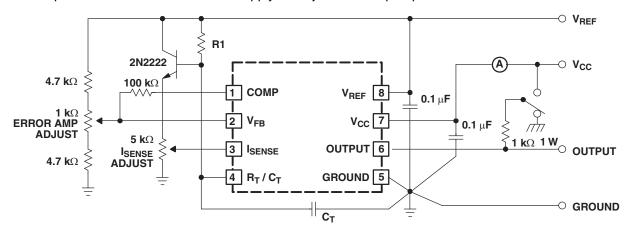


#### ERROR AMPLIFIER OPEN-LOOP FREQUENCY RESPONSE



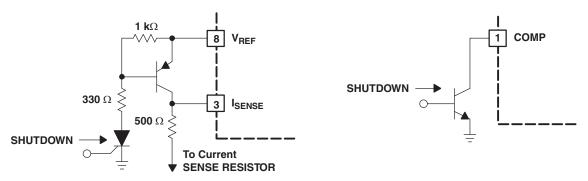
#### **OPEN-LOOP LABORATORY FIXTURE**

High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypas capacitors should be conected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.



#### SHUTDOWN TECHNIQUES

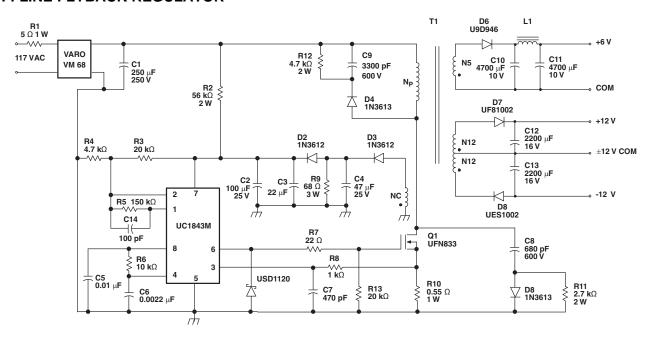
Shutdown of the UC1843 can be accomplished by two methods; either raise pin 3 above 1 V or pull pin 1 below a voltage two diode drops above ground. Either method causses the output of the PWM comparator to be high (refer to block diagram). The PWM latch is reset dominant so that the output will remain low until the next clock cycle after the shutdown condition at pin 1 and/or 3 is removed. In one example, an externally latched shutdown may be accomplished by adding an SCR which will be reset by cycling V<sub>CC</sub> below the lower UVLO threshold. At this pint the reference turns off, allowing the SCR to reset.



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#### OFFLINE FLYBACK REGULATOR

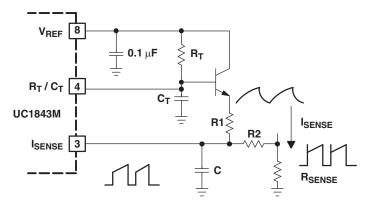


#### **Power Supply Specifications**

- 1. Input Voltages
  - a. 5VAC to 130VA (50 Hz/60 Hz)
- 2. Line Isolation: 3750 V
- 3. Switchng Frequency: 40 kHz
- 4. Efficiency at Full Load 70%
- 5. Output Voltage:
  - a. +5 V, ±5%; 1A to 4A load
    - Ripple voltage: 50 mV P-P Max
  - b. +12 V, ±3%; 0.1A to 0.3A load
    - Ripple voltage: 100 mV P-P Max
  - c. -12 V, ±3%; 0.1A to 0.3A load Ripple voltage: 100 mV P-P Max

#### **SLOPE COMPENSATION**

A fraction of the oscillator ramp can be resistively summed with the current sense signal to provide slope compensation for converters requiring duty cycles over 50%.





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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
UC1843MKGD1	ACTIVE	XCEPT	KGD	0	100	RoHS & Green	Call TI	N / A for Pkg Type	-55 to 125		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF UC1843-HIREL:

# **PACKAGE OPTION ADDENDUM**

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Space : UC1843-SP

NOTE: Qualified Version Definitions:

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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